

# PHK28NQ03LT

TrenchMOS™ logic level FET

Rev. 01 — 12 December 2002

Product data

## 1. Product profile

### 1.1 Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™ technology.

Product availability:

PHK28NQ03LT in SOT96-1 (SO8).

### 1.2 Features

- Logic level compatible
- Low gate charge.

### 1.3 Applications

- DC to DC converters
- Switched mode power supplies.

### 1.4 Quick reference data

- $V_{DS} \leq 30 \text{ V}$
- $I_D \leq 23.7 \text{ A}$
- $P_{tot} \leq 6.25 \text{ W}$
- $R_{DS(on)} \leq 6.5 \text{ m}\Omega$ .

## 2. Pinning information

Table 1: Pinning - SOT96-1 simplified outline and symbol

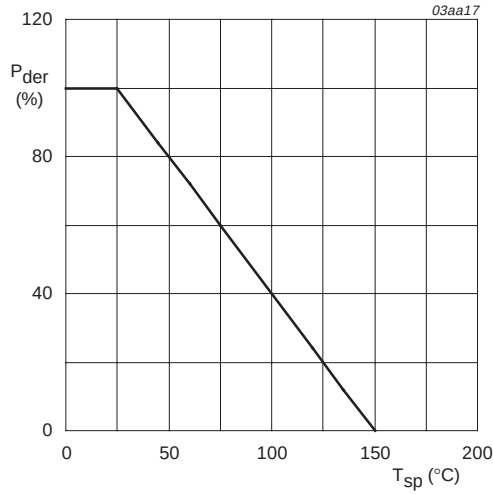
| Pin     | Description | Simplified outline                                 | Symbol        |
|---------|-------------|----------------------------------------------------|---------------|
| 1,2,3   | source (s)  | <p>Top view MBK187</p> <p><b>SOT96-1 (SO8)</b></p> | <p>MBB076</p> |
| 4       | gate (g)    |                                                    |               |
| 5,6,7,8 | drain (d)   |                                                    |               |

### 3. Limiting values

**Table 2: Limiting values**

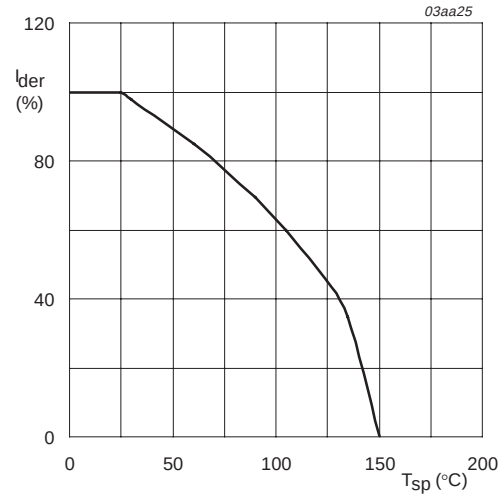
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol                    | Parameter                           | Conditions                                                                           | Min | Max  | Unit |
|---------------------------|-------------------------------------|--------------------------------------------------------------------------------------|-----|------|------|
| $V_{DS}$                  | drain-source voltage (DC)           | $25\text{ °C} \leq T_j \leq 150\text{ °C}$                                           | -   | 30   | V    |
| $V_{DGR}$                 | drain-gate voltage (DC)             | $25\text{ °C} \leq T_j \leq 150\text{ °C}$ ; $R_{GS} = 20\text{ k}\Omega$            | -   | 30   | V    |
| $V_{GS}$                  | gate-source voltage                 |                                                                                      | -   | 20   | V    |
| $I_D$                     | drain current (DC)                  | $T_{sp} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; <b>Figure 2 and 3</b>             | -   | 23.7 | A    |
|                           |                                     | $T_{sp} = 100\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; <b>Figure 2</b>                  | -   | 15   | A    |
| $I_{DM}$                  | peak drain current                  | $T_{sp} = 25\text{ °C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; <b>Figure 3</b> | -   | 60   | A    |
| $P_{tot}$                 | total power dissipation             | $T_{sp} = 25\text{ °C}$ ; <b>Figure 1</b>                                            | -   | 6.25 | W    |
| $T_{stg}$                 | storage temperature                 |                                                                                      | -55 | +150 | °C   |
| $T_j$                     | junction temperature                |                                                                                      | -55 | +150 | °C   |
| <b>Source-drain diode</b> |                                     |                                                                                      |     |      |      |
| $I_S$                     | source (diode forward) current (DC) | $T_{sp} = 25\text{ °C}$                                                              | -   | 5.2  | A    |
| $I_{SM}$                  | peak source (diode forward) current | $T_{sp} = 25\text{ °C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$                   | -   | 20.8 | A    |



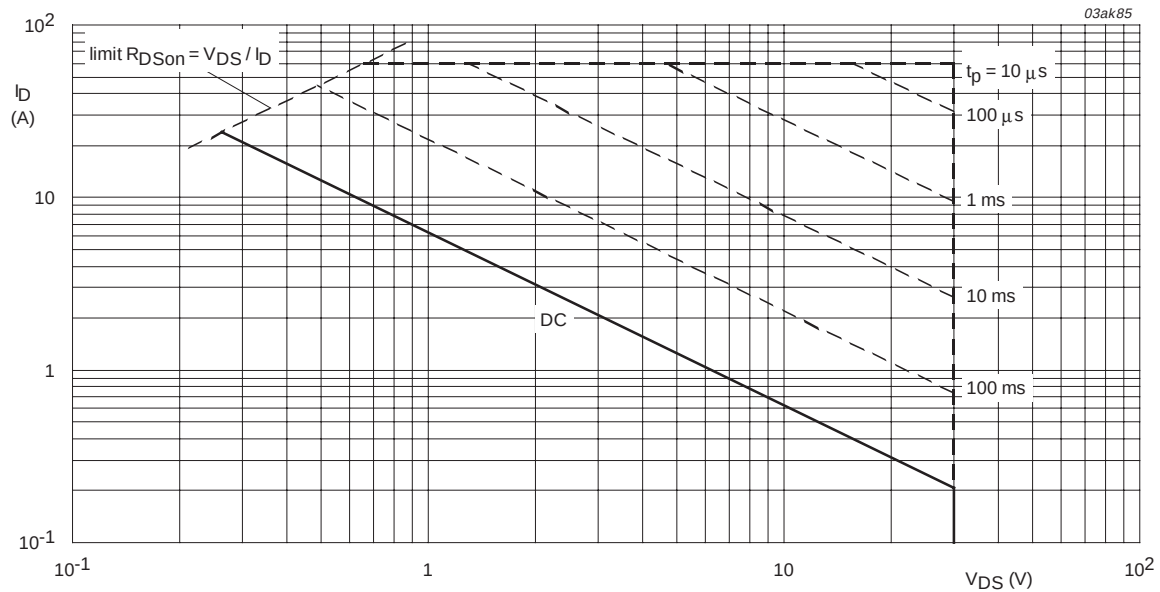
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

**Fig 1.** Normalized total power dissipation as a function of solder point temperature.



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100\%$$

**Fig 2.** Normalized continuous drain current as a function of solder point temperature.



$T_{sp} = 25^{\circ}\text{C}$ ;  $I_{DM}$  is single pulse;  $V_{GS} = 10\text{V}$

**Fig 3.** Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

4. Thermal characteristics

Table 3: Thermal characteristics

| Symbol         | Parameter                                        | Conditions | Min | Typ | Max | Unit |
|----------------|--------------------------------------------------|------------|-----|-----|-----|------|
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | Figure 4   | -   | -   | 20  | K/W  |

4.1 Transient thermal impedance

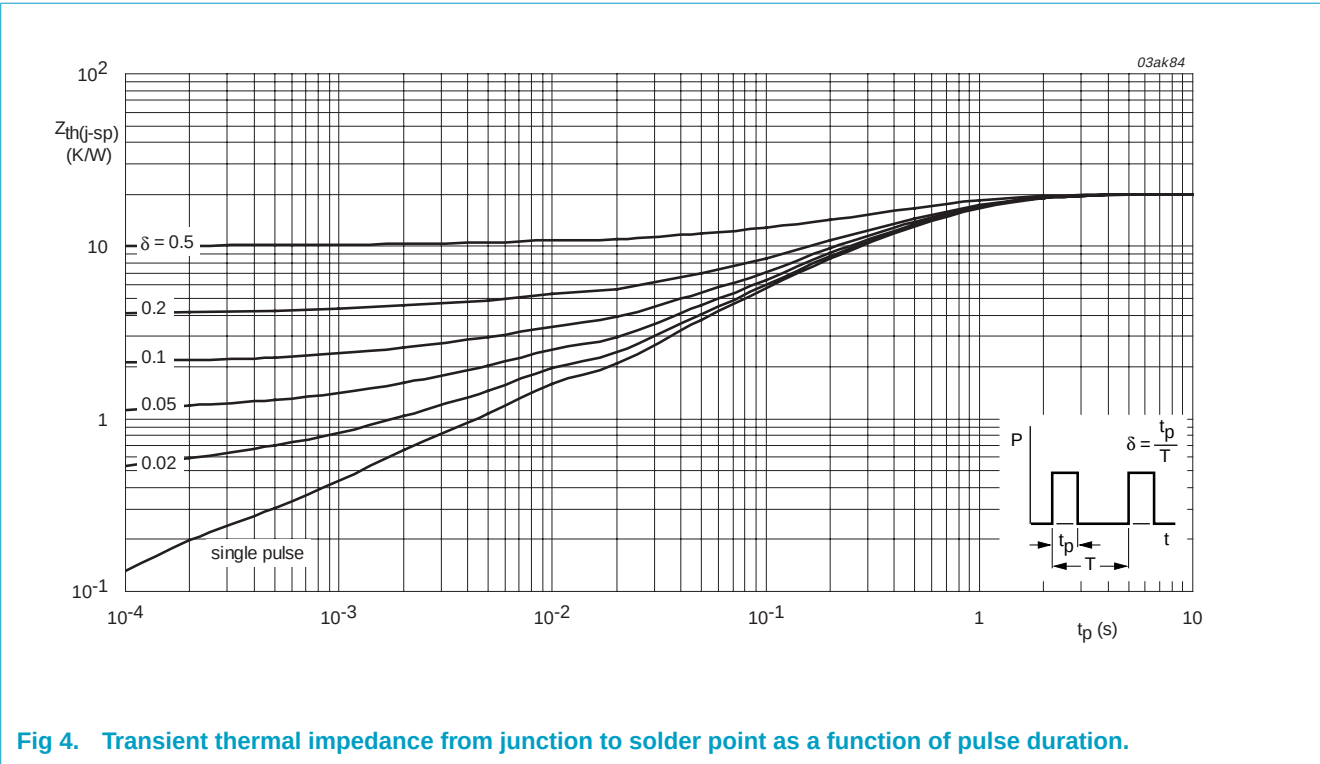


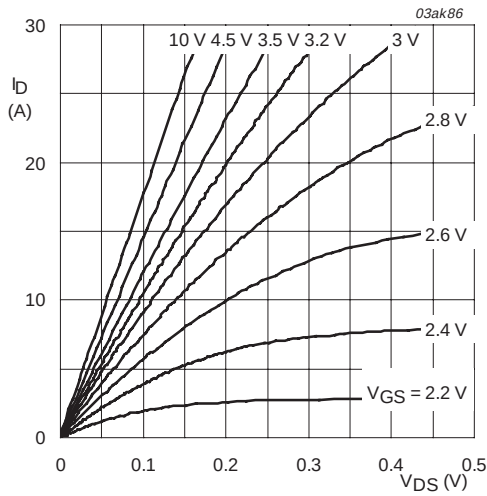
Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration.

## 5. Characteristics

**Table 4: Characteristics**

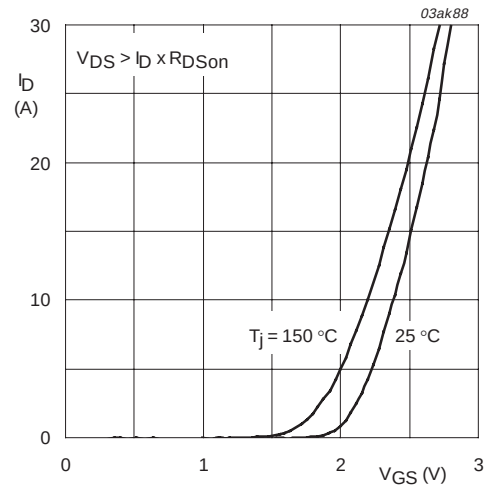
$T_j = 25\text{ °C}$  unless otherwise specified

| Symbol                         | Parameter                            | Conditions                                                                                           | Min | Typ  | Max  | Unit          |
|--------------------------------|--------------------------------------|------------------------------------------------------------------------------------------------------|-----|------|------|---------------|
| <b>Static characteristics</b>  |                                      |                                                                                                      |     |      |      |               |
| $V_{(BR)DSS}$                  | drain-source breakdown voltage       | $I_D = 250\text{ }\mu\text{A}$ ; $V_{GS} = 0\text{ V}$                                               |     |      |      |               |
|                                |                                      | $T_j = 25\text{ °C}$                                                                                 | 30  | -    | -    | V             |
|                                |                                      | $T_j = -55\text{ °C}$                                                                                | 27  | -    | -    | V             |
| $V_{GS(th)}$                   | gate-source threshold voltage        | $I_D = 1\text{ mA}$ ; $V_{DS} = V_{GS}$ ; <b>Figure 9</b>                                            |     |      |      |               |
|                                |                                      | $T_j = 25\text{ °C}$                                                                                 | 1   | 1.5  | 2    | V             |
|                                |                                      | $T_j = 150\text{ °C}$                                                                                | 0.6 | -    | -    | V             |
|                                |                                      | $T_j = -55\text{ °C}$                                                                                | -   | -    | 2.2  | V             |
| $I_{DSS}$                      | drain-source leakage current         | $V_{DS} = 30\text{ V}$ ; $V_{GS} = 0\text{ V}$                                                       |     |      |      |               |
|                                |                                      | $T_j = 25\text{ °C}$                                                                                 | -   | 0.05 | 1    | $\mu\text{A}$ |
|                                |                                      | $T_j = 150\text{ °C}$                                                                                | -   | -    | 500  | $\mu\text{A}$ |
| $I_{GSS}$                      | gate-source leakage current          | $V_{GS} = \pm 16\text{ V}$ ; $V_{DS} = 0\text{ V}$                                                   | -   | 10   | 100  | nA            |
| $R_{DS(on)}$                   | drain-source on-state resistance     | $V_{GS} = 4.5\text{ V}$ ; $I_D = 13\text{ A}$ ; <b>Figure 7 and 8</b>                                |     |      |      |               |
|                                |                                      | $T_j = 25\text{ °C}$                                                                                 | -   | 6.6  | 7.7  | m $\Omega$    |
|                                |                                      | $T_j = 150\text{ °C}$                                                                                | -   | 11.2 | 13.1 | m $\Omega$    |
|                                |                                      | $V_{GS} = 10\text{ V}$ ; $I_D = 14\text{ A}$ ; <b>Figure 7 and 8</b>                                 | -   | 5.5  | 6.5  | m $\Omega$    |
| <b>Dynamic characteristics</b> |                                      |                                                                                                      |     |      |      |               |
| $Q_{g(tot)}$                   | total gate charge                    | $I_D = 14\text{ A}$ ; $V_{DD} = 15\text{ V}$ ; $V_{GS} = 4.5\text{ V}$ ; <b>Figure 13</b>            | -   | 30.3 | -    | nC            |
| $Q_{gs}$                       | gate-source charge                   |                                                                                                      | -   | 11.4 | -    | nC            |
| $Q_{gd}$                       | gate-drain (Miller) charge           |                                                                                                      | -   | 7.8  | -    | nC            |
| $C_{iss}$                      | input capacitance                    | $V_{GS} = 0\text{ V}$ ; $V_{DS} = 20\text{ V}$ ; $f = 1\text{ MHz}$ ; <b>Figure 11</b>               | -   | 2800 | -    | pF            |
| $C_{oss}$                      | output capacitance                   |                                                                                                      | -   | 670  | -    | pF            |
| $C_{rss}$                      | reverse transfer capacitance         |                                                                                                      | -   | 320  | -    | pF            |
| $t_{d(on)}$                    | turn-on delay time                   | $V_{DD} = 15\text{ V}$ ; $R_L = 15\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; $R_G = 6\text{ }\Omega$ | -   | 11   | -    | ns            |
| $t_r$                          | rise time                            |                                                                                                      | -   | 10   | -    | ns            |
| $t_{d(off)}$                   | turn-off delay time                  |                                                                                                      | -   | 80   | -    | ns            |
| $t_f$                          | fall time                            |                                                                                                      | -   | 40   | -    | ns            |
| <b>Source-drain diode</b>      |                                      |                                                                                                      |     |      |      |               |
| $V_{SD}$                       | source-drain (diode forward) voltage | $I_S = 2.3\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; <b>Figure 12</b>                                      | -   | 0.72 | 1.2  | V             |



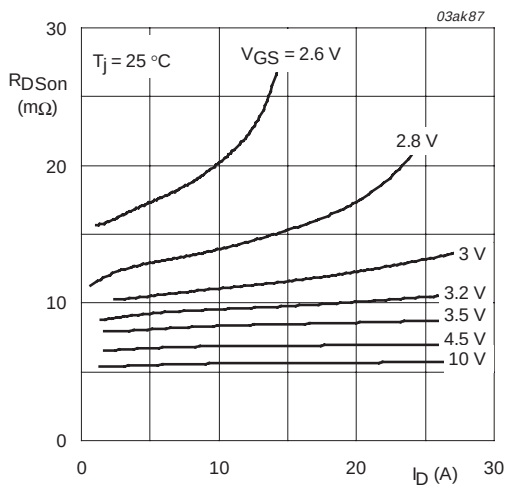
$T_j = 25^\circ\text{C}$

**Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.**



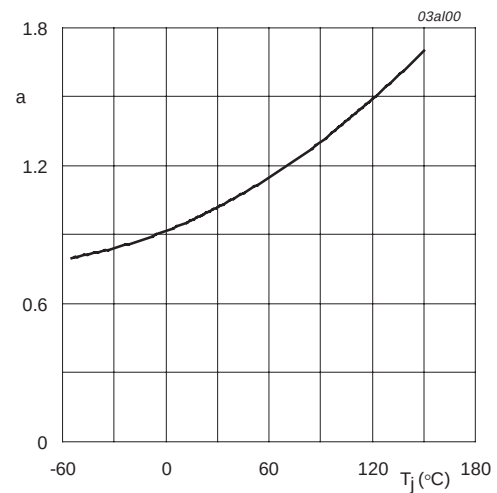
$T_j = 25^\circ\text{C}$  and  $150^\circ\text{C}$ ;  $V_{DS} > I_D \times R_{DSon}$

**Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.**



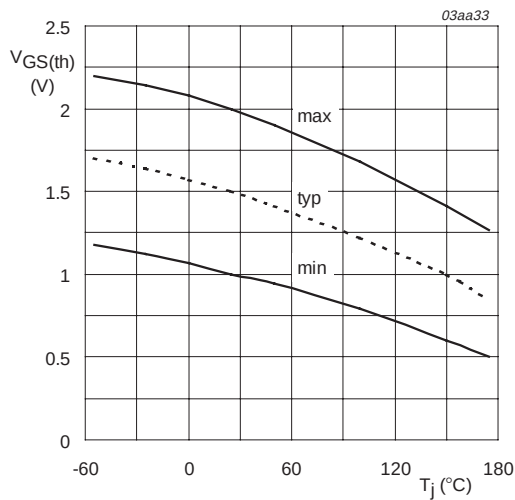
$T_j = 25^\circ\text{C}$

**Fig 7. Drain-source on-state resistance as a function of drain current; typical values.**



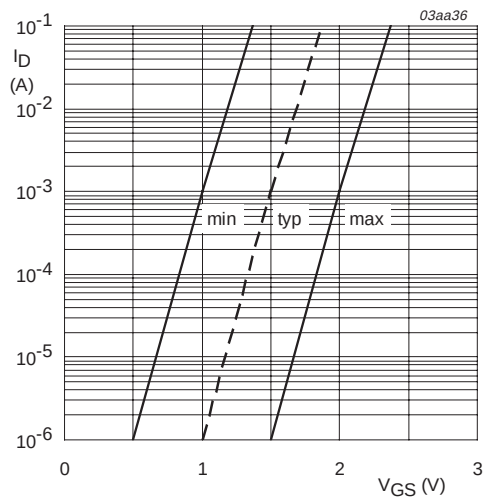
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

**Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.**



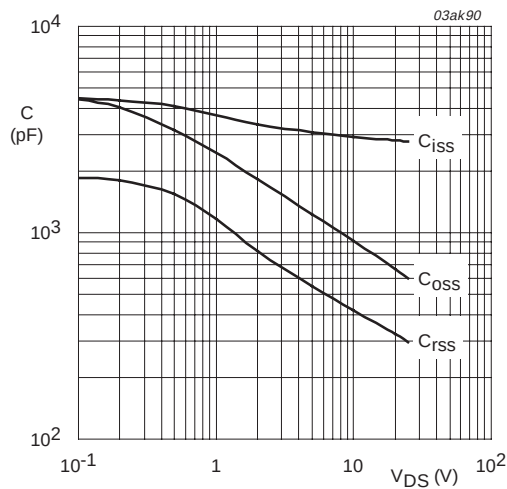
$I_D = 1\text{ mA}$ ;  $V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



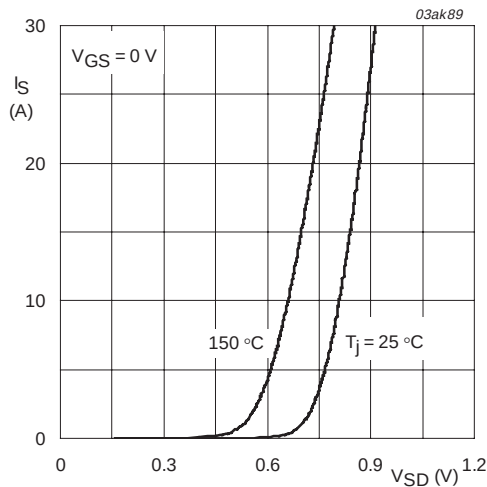
$T_j = 25\text{ °C}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



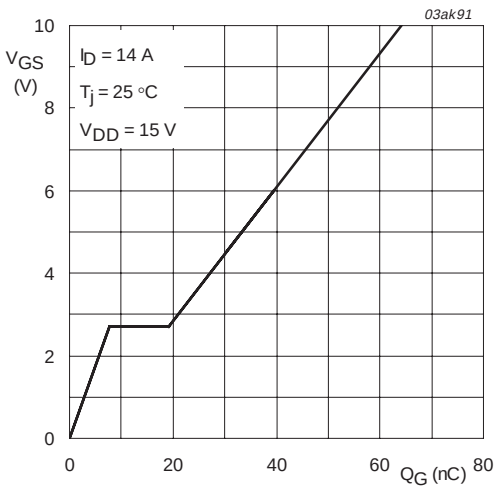
$V_{GS} = 0\text{ V}$ ;  $f = 1\text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_J = 25$  °C and  $150$  °C;  $V_{GS} = 0$  V

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 14$  A;  $V_{DD} = 15$  V

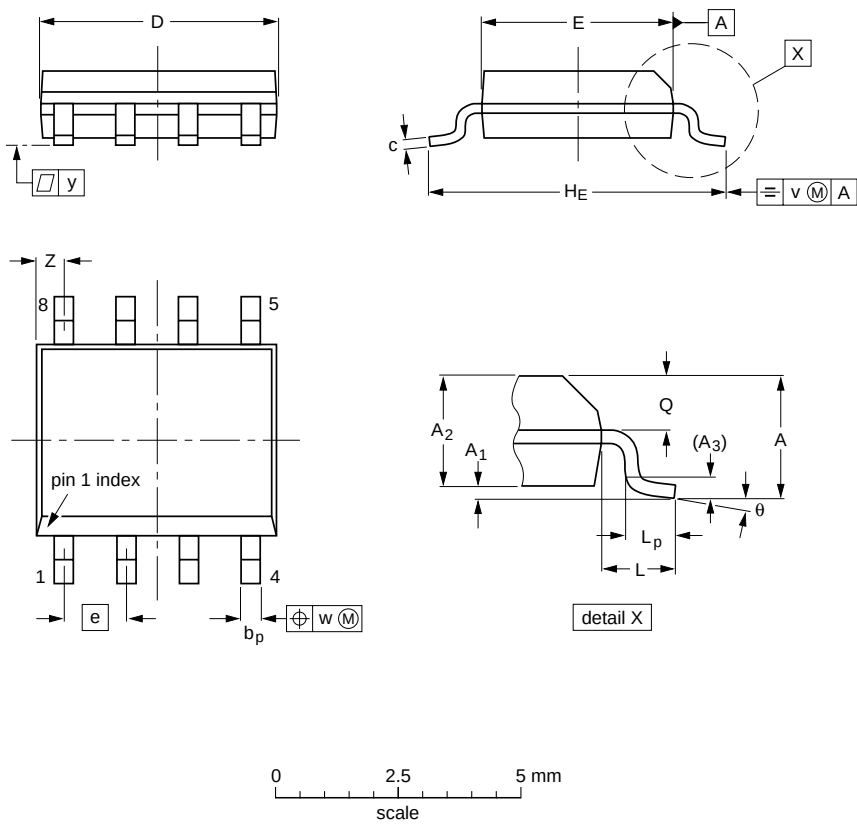
Fig 13. Gate-source voltage as a function of gate charge; typical values.



6. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT   | A<br>max. | A <sub>1</sub> | A <sub>2</sub> | A <sub>3</sub> | b <sub>p</sub> | c                | D <sup>(1)</sup> | E <sup>(2)</sup> | e     | H <sub>E</sub> | L     | L <sub>p</sub> | Q              | v    | w    | y     | z <sup>(1)</sup> | θ        |
|--------|-----------|----------------|----------------|----------------|----------------|------------------|------------------|------------------|-------|----------------|-------|----------------|----------------|------|------|-------|------------------|----------|
| mm     | 1.75      | 0.25<br>0.10   | 1.45<br>1.25   | 0.25           | 0.49<br>0.36   | 0.25<br>0.19     | 5.0<br>4.8       | 4.0<br>3.8       | 1.27  | 6.2<br>5.8     | 1.05  | 1.0<br>0.4     | 0.7<br>0.6     | 0.25 | 0.25 | 0.1   | 0.7<br>0.3       | 8°<br>0° |
| inches | 0.069     | 0.010<br>0.004 | 0.057<br>0.049 | 0.01           | 0.019<br>0.014 | 0.0100<br>0.0075 | 0.20<br>0.19     | 0.16<br>0.15     | 0.050 | 0.244<br>0.228 | 0.041 | 0.039<br>0.016 | 0.028<br>0.024 | 0.01 | 0.01 | 0.004 | 0.028<br>0.012   |          |

- Notes
- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
  - 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE<br>VERSION | REFERENCES |        |      |  | EUROPEAN<br>PROJECTION | ISSUE DATE           |
|--------------------|------------|--------|------|--|------------------------|----------------------|
|                    | IEC        | JEDEC  | EIAJ |  |                        |                      |
| SOT96-1            | 076E03     | MS-012 |      |  |                        | 97-05-22<br>99-12-27 |

Fig 14. SOT96-1 (SO8).

## 7. Revision history

Table 5: Revision history

| Rev | Date     | CPCN | Description                   |
|-----|----------|------|-------------------------------|
| 01  | 20021212 | -    | Product data (9397 750 10743) |

## 8. Data sheet status

| Level | Data sheet status <sup>[1]</sup> | Product status <sup>[2][3]</sup> | Definition                                                                                                                                                                                                                                                                                     |
|-------|----------------------------------|----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| I     | Objective data                   | Development                      | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.                                                                                                    |
| II    | Preliminary data                 | Qualification                    | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.             |
| III   | Product data                     | Production                       | This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). |

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## 9. Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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For sales office addresses, send e-mail to: [sales.addresses@www.semiconductors.philips.com](mailto:sales.addresses@www.semiconductors.philips.com).

Fax: +31 40 27 24825

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